



## Material Content Data Sheet



<b>Sales Product Name</b>		SPD01N60C3		<b>Issued</b>		1. August 2018		
<b>MA#</b>		MA000851396						
<b>Package</b>		PG-TO252-3-311		<b>Weight*</b>		312.93 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.893	0.29	0.29	2854	2854
leadframe	inorganic material	phosphorus	7723-14-0	0.043	0.01		137	
	non noble metal	iron	7439-89-6	0.143	0.05		458	
	non noble metal	copper	7440-50-8	143.098	45.71	45.77	457284	457879
	non noble metal	aluminium	7429-90-5	0.530	0.17	0.17	1695	1695
wire	inorganic material	antimonytrioxide	1309-64-4	2.014	0.64		6437	
encapsulation	plastics	brominated resin	-	2.158	0.69		6896	
	organic material	carbon black	1333-86-4	2.302	0.74		7356	
	plastics	epoxy resin	-	19.423	6.21		62067	
	inorganic material	silicondioxide	60676-86-0	117.975	37.70	45.98	377002	459758
leadfinish	non noble metal	tin	7440-31-5	3.740	1.20	1.20	11952	11952
plating	inorganic material	phosphorus	7723-14-0	0.000	0.00		1	
	non noble metal	nickel	7440-02-0	0.086	0.03	0.03	276	277
solder	non noble metal	tin	7440-31-5	0.026	0.01		84	
	noble metal	silver	7440-22-4	0.033	0.01		106	
	non noble metal	lead	7439-92-1	1.262	0.40	0.42	4032	4222
heatspreader	inorganic material	phosphorus	7723-14-0	0.006	0.00		18	
	non noble metal	iron	7439-89-6	0.019	0.01		61	
	non noble metal	copper	7440-50-8	19.177	6.13	6.14	61284	61363
*deviation	< 10%		Sum in total:			100.00		1000000

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com